

ICSICT 2022

International Conference on Solid-State and Integrated Circuit Technology

Oct. 25-28, 2022

Nanjing Platinum Hanjue Hotel
Nanjing, China

<http://www.icsict.com>

CALL FOR PAPERS

The ICSICT-2022 conference is the 16th in the series aiming to provide an international forum for the presentation and discussion of recent advances in solid-state and integrated circuit technology. The conference will be held on Oct.25-28, 2022 in Nanjing, China. All aspects of solid-state devices, circuits, process technologies, materials and other related research are within the scope of the conference. The three days of contributed and invited presentations on the latest developments in diverse fields given in oral and poster sessions, panel discussions on leading edge technology issues, and other activities will provide extensive opportunities for technical information exchange as well as a stimulating environment for mutual communication among participants. The **Best Student Paper Award** and the **Best Paper Award for Outstanding Young Scholars** will be presented at the closing of the conference.

PAPER SUBMISSION

Prospective authors are requested to submit **3 pages** camera-ready full length paper in English for proceedings publication. The proceedings will have an IEEE catalogue number and will be collected in IEEE publication database ---- IEEE X^{press} .

Deadline for Camera-Ready Full-Length Paper Submission:

June 30, 2022

Notification of Acceptance:

Aug.15, 2022

On-line submission at <http://www.icsict.com> is required.

About paper submission, please contact:

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THE SCOPE AND TOPICS OF THE CONFERENCE

(Papers are solicited in, but not limited to the following areas)

VLSI Technologies

1. Advanced CMOS Logic Devices
2. Advanced Process Technologies
3. Advanced Interconnect Technologies
4. Power Devices Technologies
5. 2D Devices & Technologies
6. Thin Film Devices and Technologies
7. Compound Semiconductor Technologies
8. Microwave, Millimeter Wave and Analog
9. New Non-Volatile Memory Technologies
10. Flash & 3D Memory Technologies
11. Optoelectronics and Silicon Photonics
12. Sensor, MEMS, and Bioelectronics
13. Emerging Semiconductor Materials & Devices
14. 3D Integration
15. Technologies for Quantum & Novel Computing
16. Advanced & Heterogeneous Packaging
17. Logic and Power Device Reliability
18. Memory Device Reliability
19. Back-End of Line Reliability & ESD
20. Device Modeling & Simulation
21. Process Modeling & Simulation
22. Design & Technology Co-Optimization

VLSI Circuits & ICCAD

23. Digital Module & Circuit
24. Analog Module & Circuit
25. Mixed-Signal Circuit & ADC/DACs
26. RF Module & Circuit
27. Memory Circuits
28. SoC For IoT and other applications
29. Processor & Advanced Computing System
30. Efficient AI Circuit
31. Wireline and Optical Communication Circuit
32. FPGA Circuits
33. Advanced Clock
34. Signal Processing
35. Chip Test and Reliability
36. EDA Technology for Circuit Design

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